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TITLE : HIGH-TEMPERATURE SOLDER

ABSTRACT : PURPOSE: To provide the high-temp. solder having excellent a high-temp. characteristic and thermal fatigue characteristic by adding specific ratios of silver and copper to the solder.

CONSTITUTION: This solder consists of an alloy having a compsn. contg. 3.0% cover and ≤ 5.0 wt.% Ag, 0.5 to 3.0wt.% Cu, and the balance Sn. Further, the alloy may contain $\leq 5\%$ Sb. The solder is constituted by compounding the alloy particles having the above-mentioned compsn. and flux components. The solder has the high-temp. characteristics of 210 to 230°C m.p. and 1 to 2kgf/mm² at 150°C and has the thermal fatigue characteristic of -55°C to 125°C×1000 cycles or above.

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